Supplementary material for

Optimization of hot embossing condition using Taguchi method and evaluation of microchannels for flexible on-chip PEMFC

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Figure S1 shows more details about our self-made hot embossing equipment.

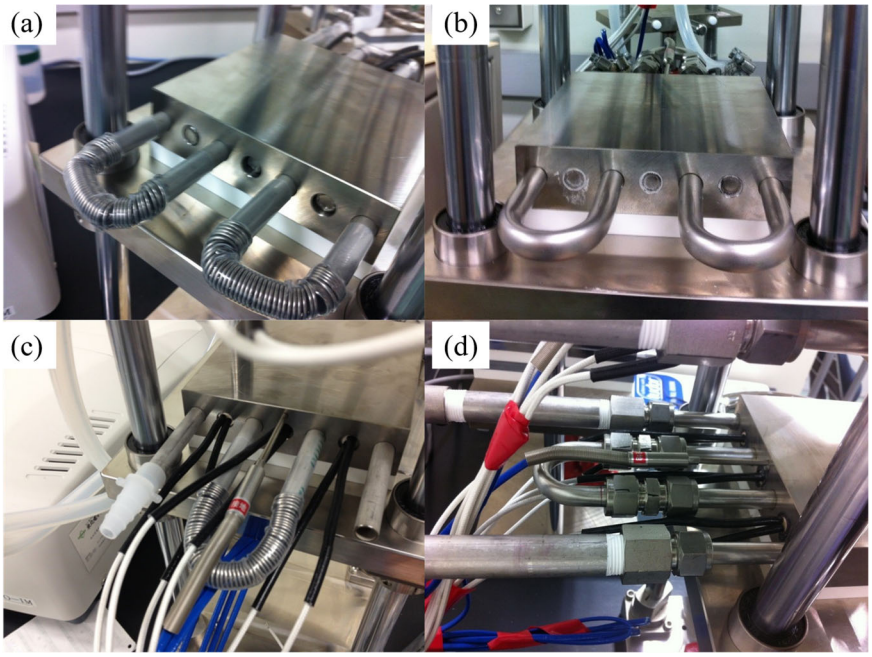


Figure S1 Self-made micro hot embossing system: (a) A thermocouple is arranged below the hot embossing platform. (b) Front view of the hot embossing platform (c) The piping layout of the hot embossing platform (d) Complete piping connection

Figure S2 shows the master mold structure (mold II) used in the experiment.

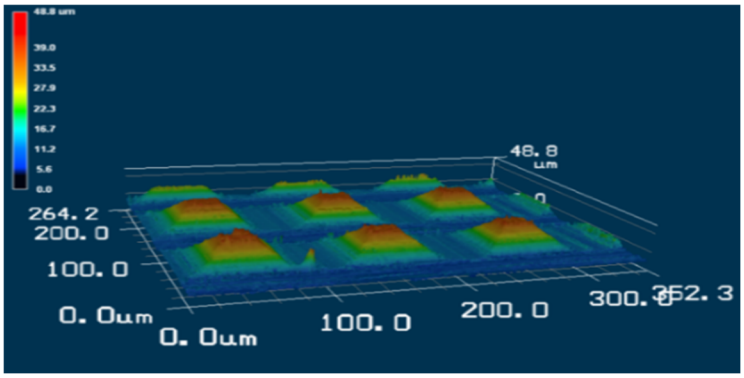


Figure S2 The master mold structure (mold II) used in the experiment